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### THE HUNGARIAN CONNECTION

Andy Grove (1936-2015) alias Gróf András

EETimes 3/2016:

Andy Grove a Hungarian immigrant who survived Nazi occupation (and the arrow-cross Hungarian Nazi terror...) and vent on to be instrumental in the formation of Intel Corp. And its rise to become the biggest semiconductor company in the world, died Monday (March 21) at he age of 79.

Though not credited as a co-founder, Grove was present for Intel1s early history, beginning in 1968.

Company's president 1979 to 1997, CEO from 1987 to 1998.

Chairman of board of directors from 1997 to 2005.

Grove was an enormously influential figure in the semiconductor industry and beyond. At Intel, he presided over the company's transformation from a supplier of memory chips into the world's biggest microprocessor vendor.

### THE HUNGARIAN CONNECTION

During Grove's tenure as CEO Intel's market capitalization increased from \$4billion to \$197billion. During that time Intel's annual revenue increased from \$1,9 billion to more than \$26 billion (about 7000 billion HUF, roughly 25 % of Hungary's GDP).

Grove immigrated to the U.S. in 1957 after surviving both the Nazi occupation and arrow-cross terror and the subsequent repressions in and Sovietization of Hungary. He studied chemical engineering at the City College of New York and completed his Ph.D. at the University of California-Berkeley in 1993.

Grove was hired to Fairchild Semiconductor by Gordon Moore as a researcher in 1963. When Moore and Robert Noyce left Fairchild to found Intel in 1968, Grove was their first hire.

### THE HUNGARIAN CONNECTION

"Andy approached corporate strategy and leadership in ways that continue to influence prominent thinkers and companies around the world", said Intel Chairman Andy Bryant. " He combined the analytic approach of a scientist with an ability to engage others in a honest and deep conversation, which sustained Intel's success over a period that saw the rise of the personal computer, the Internet and Silicon Valley."

### LOGIC CIRCUITS GENERATIONS AND FAMILIES

The circuit technologies are the relevant factors which determine and characterize the generations of logic circuits.

A logic family of monolithic digital integrated devices is a group of electronic logic gates, flip-flops, etc., constructed using one of several different designs and technology, usually with compatible logic levels and power supply characteristic within the family.

Before the widespread use of integrated circuits, various vacuum-tube and solid-state logic systems were in use, but these were never as standardized and interoperable as the IC devices.

### LOGIC CIRCUIT GENERATIONS

1930s, relay circuits, Bell Labs (driving force: telephone exchange switching)

1940s, vacuum tubes e.g. ENIAC, built in 1946 (electronic numerical integrator and calculator), calculated the trajectory of an artillery shell in only 30 sec. Large and expensive...

18 thousand vacuum tubes 60 thousand pounds (27 thousand kg) 16200 cubic feet (480 m<sup>3</sup>) 174 kW

(c.f. four-operation hand-held calculator appr. 9 000 transistors)

(driving force: military applications, artillery shell trajectory calculations)



### LOGIC CIRCUIT GENERATIONS: ENIAC

ENIAC could add 5000 numbers in one second.

The amount of energy ENIAC expended to compute a single shell trajectory was comparable to that of the explosive discharge required to actually fire the shell.

ENIAC was still the fastest computer on the Earth nine years later, when it was turned off because the US Army could no longer justify the expense of operating and maintaining it.

### **LOGIC CIRCUIT GENERATIONS (2)**

1950/1960 semiconductor diode and transistor circuits

- RTL resistor-transistor-logic
- DTL diode-transistor-logic
- ECL emitter-coupled logic (later)

From 1961 SSI (above listed on one chip)

1960s TTL (transistor-transistor logic), Sylvania, then Texas Instruments, the TI system later became the *de-facto* industry standard

After 1960/1970: MOS metal oxide semiconductor: pMOS (1960s) then nMOS (1970s)

1980s CMOS (complementary metal-oxide-semiconductor) introduced in 1968 by RCA





















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### THE PEOPLE



William Shockley (1910-1989)

The brilliant director of the transistor effort, *Shockley*'s research in the behavior of electronics in crystals introduced him to Bardeen and Brattain, who aided him in his experimentation to build working models of transistor mechanisms. Spurned on by their demonstration of a working point-contact transistor, *Shockley* created the junction transistor, which became the fundamental structure of transistor developments to come.

Shockley left Bell Labs in 1955 to establish Shockley Semiconductor Laboratory (part of Beckman Instruments, Inc.), an effort that was instrumental in the birth of Silicon Valley and the electronics industry. Several of his former employees left his company to found what later became Intel, the most successful microprocessor company in the world. <sup>25</sup>











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### THE MOSES OF SILICON VALLEY



SENIOR STAFF of the Shockley Semiconductor Laboratory toast their boss at a luncheon the day after the announcement of his Nobel Prize in 1956. These are the men who introduced Bell Laboratories' silicon technology to California. Gordon Moore is sitting at the far left; Robert Noyce is standing fourth from left and Jay Last is standing fourth from left and Jay Last is standing at the far inght, just to the right of William Shockley, who is seated at the end of the table. (Courtesy of Intel Corporation.)

### **1960: THE Si IC PATENT (FAIRCHILD)**



A page from the original patent by R. Noyce:

### SEMICONDUCTOR DEVICE-AND-LEAD STRUCTURE

Filed: July 2?, 1960 Published: April 25, 1961, 2981877

### Si INTEGRATED CIRCUIT



1959: planar process Jean Hoerni and Robert Noyce

1961: first commercial planar IC (two transistors in a flip-flop circuit) Fairchild



### **1958: INTEGRATED CIRCUIT**



1958: first integrated circuit (Ge) *Jack Kilby*, Texas Instruments Physics Nobel Prize 2000 (shared with *Zhores I. Alferov* and *H. Kroeme*r)











pical Si npn	transistor pa	arameters	
Region	V <sub>BE</sub> (V)	V <sub>CE</sub> (V)	Current Relation
Cutoff	< 0.6	Open circuit	I <sub>B</sub> =I <sub>C</sub> =0
Active	0.6-0.7	> 0.8	$I_{\rm C} = h_{\rm FE} I_{\rm B}$
Saturation	0.7-0.8	0.2	$I_B \ge I_C / h_{FE}$

### **IC: THE SI BIPOLAR TRANSISTOR**

 Typical dimensions: emitter diffusion ~(2-2.5) μm base diffusion ~4 μm n-epitaxial layer (collector) ~10 μm emitter window (small current transistor, ~1 mA) (10-15) x (10-15) μm

E.g. in a TTL circuit one emitter is 16 x 16  $\mu$ m, the nominal input current is max 1.6 mA (current density 6.25 A/mm<sup>2</sup>).











## TRANSISTOR-TRANSISTOR LOGIC TTL

The original basic TTL gate was a slight improvement over the DTL gate.

There are several TTL subfamilies or series of the TTL technology.

Has a number start with 74 and follows with a suffix that identifies the series type, e.g. 7404, 74S86, 74ALS161.

Three different types of output configurations:

- 1. open-collector output
- 2. Totem-pole output
- 3. Three-state (or tristate) output

74 – standard

54 – military

84 - industrial (discontinued)



### SCHOTTKY TTL: AN INTRODUCTION

Transistor in bipolar logic (standard TTL) are saturated switches - minority carrier storage limits the speed of the device.

Variations of the standard TTL design to reduce these effects and improve speed, power consumption, or both.

"Schottky transistors" i.e. junction transistors with integrated Schottky barrier clamping diodes between the collector and basis reduce or prevent charge storage, leading to faster switching gates.

Incorporating Schottky barrier diodes into the TTL design, the switching speed can be reduced to 2 ... 5 nsec, a half or full order of magnitude improvement with respect to conventional design.

### **SCHOTTKY DIODE I-V CHARACTERISTICS**

- Schottky diode is a metal-semiconductor (MS) diode
- · Historically, Schottky diodes are the oldest diodes
- MS diode electrostatics and the general shape of the MS diode I-V characteristics are similar to p<sup>+</sup>n diodes, but the details of current flow are different.
- Dominant currents in a p<sup>+</sup>n diode
- arise from recombination in the depletion layer under small forward bias.
- arise from hole injection from p<sup>+</sup> side under larger forward bias.
- Dominant currents in a MS Schottky diodes
- Electron injection from the semiconductor to the metal.





### **I-V CHARACTERISTICS**

 $I = I_{\rm s} \left( e^{\frac{qV_{\rm A}}{kT}} - 1 \right) \quad \text{where} \quad I_{\rm s} = A \mathcal{A}^* T^2 e^{-\frac{\Phi_{\rm B}}{kT}}$ 

where  $\Phi_{B}$  is Schottky barrier height,  $V_{A}$  is applied voltage, A is area, and  $A^{*}$  is Richardson's constant.

The reverse leakage current for a Schottky diode is generally much larger than that for a p<sup>+</sup>n diode.

Since MS Schottky diode is a majority carrier devices, the frequency response of the device is much higher than that of equivalent  $p^+$  n diode.



### **BASIC SCHOTTKY TTL NAND GATE**



Features:

Transistors: all clamped with Schottky diode except Q4 (this does not saturate) Input diodes: high-speed clamping of input signal excursions below ground Q5: Emitter follower to speed up 0-to-1 switching of output 50 ohm resistor: Low-to-high transient switching current reduction and impedance matching











### **BICMOS: APPLICATION EXAMPLES**

Carry look ahead in adders: the carry can be calculated from the *generate* and *propagate* combinations. Fast operation is ensured by using bipolar output stages in the implementation of

$$C_{i+1} = G_i + P_i C_i$$

allowing a fast charging of the loading capacitances.

Other example is the driving of buses, which also represent relatively large capacitive loads.

### **EMITTER COUPLED LOGIC (ECL)**

The ECL family (also called current-mode logic, CML) is the fastest logic family in the group of bipolar logic families. The characteristic features that give this logic family its high speed or short propagation delay are outlined as follows:

1. It is a nonsaturating logic. That is, the transistors in this logic are always operated in the active region of their output characteristics. They are never driven to either cutoff or saturation, which means that logic LOW and HIGH states correspond to different states of conduction of various bipolar transistors. The main factor, limiting the switching speed of TTL type circuits, the minority carrier storage is not present or at least is very weak.

### EMITTER COUPLED LOGIC (ECL)

2. The logic swing, that is, the difference in the voltage levels corresponding to logic LOW and HIGH states, is kept small (typically 0.85 V), with the result that the output capacitance needs to be charged and discharged by a relatively much smaller voltage differential.

3. The circuit currents are relatively high and the output impedance is low, with the result that the output capacitance can be charged and discharged quickly.







### **ECL BENEFITS**

ECL gates produce both true and complemented outputs.

ECL gates are fast since it the BJTs are always in forward active mode, and it only takes a few tenths of a volt to get the output to change states, hence reducing the dynamic power.

ECL gates provide near constant power supply current for all states thereby generating less noise from the other circuits.

The ECL gate structure inherently has high input impedance and low output impedance, which is very conducive to achieving large fan-out and drive capability.

### **ECL PERFORMANCE**

Different subfamilies of ECL logic include among others MECL-I, MECL-II, MECL-III, MECL 10K, MECL 10H and MECL 10E.

As an example the basic characteristic parameters of MECL-10H are as follows:

gate propagation delay=1 ns; flip-flop toggle frequency=250MHz (min.); power dissipation per gate=25 mW; delay-power product=25 pJ.

ECL performance is illustrated with data for 4 bit 10181 type adder without and with type 10179 fast carry unit

Number of bits	Add time (ns) no fast carry chip	Total add time (ns) with fast carry chip
4 8 16 24 32 64	8 11 17 23 30 54	16 (1 -79, 4 -81) 17 (1 -79, 6 -81) 19 (2 -79, 8 -81) 25 (4 -79, 16 -81)

Parameter	CMOS	TTL	ECL
Basic gate	NAND/NOR	NAND	OR/NOR
Fan-out	>50	10	25
Power per gate (mW)	1 @ 1 MHz	1 - 22	4 - 55
Noise immunity	Excellent	Good	Acceptable
t <sub>PD</sub> (ns)	1 - 200	1.5 – 33	1 - 4

### FIGURE-OF-MERIT: POWER-DELAY PRODUCT

The product of the average power consumption and average propagation delay. Since the clock cycle is limited by the propagation delay, this number is essentially the typical energy consumption per cycle per gate.

Values are currently in the picoJoule range.

On thing that makes this a good *figure-of-merit* is that many of the simple things one can do to improve (decrease) propagation delay essentially increases (degrades) the current and thus the power consumption, so the PDP remains constant.

### **POWER-DELAY PRODUCT**

"Good" circuit: small delay and small power dissipation.

Figure-of-merit: the product of these two parameters (power-delay product).

Standard 54/74 series:  $t_{od}$  = 10 nsec, P = 10 mW/gate

$$P t_{pd} = 100 pJ$$

Interpretation: approximately the energy needed to change the value of 1 bit.

### SCHOTTKY TTL: POWER-DELAY PRODUCT

54S/74S series:  $t_{pd}$  = 3 nsec, P = 19 mW/gate

 $P t_{pd} = 57 pJ$ 

54LS/74LS series:  $t_{pd}$  = 9 nsec, P = 2 mW/gate

 $P t_{pd} = 18 pJ$ 

A factor of 1.5 and 5 better than standard TTL!

### TTL AND CMOS: $P_{\tau}$ FIGURE OF MERIT

Circuit family	Propagation delay	Gate dissipation	"Jósági" tényező
	t <sub>pd</sub> [ns]	$P_{d}$ [mW]	P <sub>d</sub> *t <sub>pd</sub> [pJ]
74xx	10	10	100
74LSxx	9.5	2	19
74ASxx	1.5	2	13
74ALSxx	4	1.2	5
74Fxx	3	6	18
74HCxx	8	0.003	$24 \times 10^{-3}$
74HCTxx	14	0.003	$42 \times 10^{-3}$
74ACxx	5	0.010	$50 \times 10^{-3}$
74ACTxx	5	0.010	$50 \times 10^{-3}$
74AHCxx	5.5	0.003	$16 \times 10^{-3}$
74AHCTxx	5	0.003	$14 \times 10^{-3}$
10xxx	2	25	50
10Hxxx	1	25	25



### **BIPOLAR AND MOS COMPARISON**

Property	Bipolar	MOS
Power dissipation	medium	very small
Switching time	very small	relatively small
Input impedance	small	extremely large
Loading capability	good	very good
Noise	small	very small
Fab technology	more complex	more simple
Integration	less (in principle)	very high





### **REVIEW QUESTIONS**

1. What do you understand by the term logic family? What is the significance of the logic family with reference to digital integrated circuits (ICs)?

2. Briefly describe propagation delay, power dissipation, speed–power product, fan-out and noise margin parameters.

3. Describe the difference between the bipolar integrated circuits and MOS integrated circuits.

4. Define and describe BiCMOS logic circuits technology and circuits. What are the advantages of a BiCMOS logic circuit?

5. Define and describe basic ECL logic. With the help of a relevant circuit schematic, briefly describe the operation of ECL OR/NOR logic. What is the advantage of ECL logic family?

### **REVIEW QUESTIONS**

6. What are the Schottky diode and Schottky transitsor? Explain their relevance for digital logic circuits.

7. Define and explain the concept of power-delay product (PDP) of a logic gate as a figure-of-merit.